

## Data and signal line chokes

Common-mode chokes, ring core  
4.7 ... 10 mH, 200 ... 300 mA, 40 °C

**Series/Type:**            **B82720H14**  
**Date:**                    October 2008

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**Rated voltage 42 V AC/80 V DC**  
**Rated inductance 4.7 mH to 10 mH**  
**Rated current 200 mA to 300 mA**



### Construction

- Current-compensated ring core double choke
- Ferrite core
- Polycarbonate case (UL 94 V-0)
- Polyurethane potting (UL 94 V-0)

### Features

- Suitable for automatic insertion
- Suitable for wave soldering
- RoHS-compatible

### Applications

- Telecom switching systems
- Terminal systems
- Measuring and control lines

### Terminals

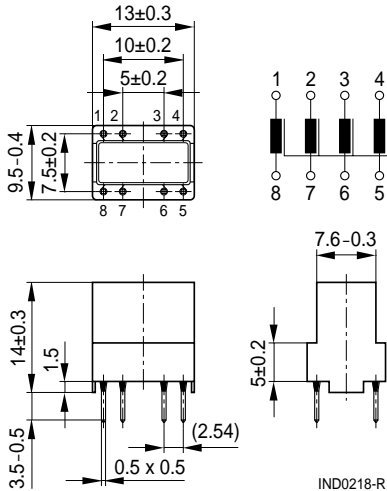
- Base material CuNi18Zn20
- Layer composition Ni, Sn
- Hot-dipped

### Marking

Manufacturer, ordering code, rated inductance, rated current, date of manufacture (YYWWDD)

### Delivery mode

Cardboard box

**Dimensional drawing and pin configuration**


Tolerances to ISO 2768-M  
unless otherwise noted.

Dimensions in mm

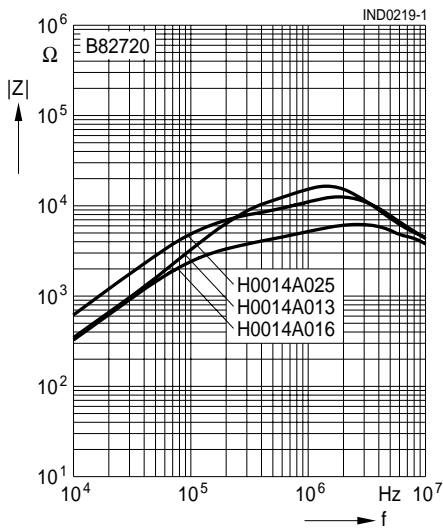
**Technical data and measuring conditions**

Rated voltage $V_R$	42 V AC (50/60 Hz) / 80 V DC
Rated temperature $T_R$	40 °C
Rated current $I_R$	Referred to 50 Hz and rated temperature
Rated inductance $L_R$	Measured with Agilent 4284A at 10 kHz, 0.1 mA, 20 °C Inductance is specified per winding.
Inductance tolerance	-30%/+50% at 20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with $I_R$ , 20 °C
Stray inductance $L_{\text{stray,typ}}$	Measured with Agilent 4284A at 10 kHz, 5 mA, 20 °C, typical values
DC resistance $R_{\text{typ}}$	Measured at 20 °C, typical values
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: (245 ±5) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	(260 ±5) °C, (10 ±1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	-25 °C ... +40 °C, ≤ 75% RH
Weight	Approx. 2.3 g

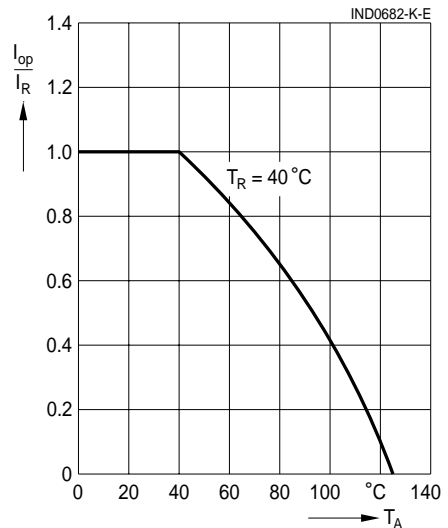
**Characteristics and ordering codes**

$L_R$ mH	$L_{\text{stray,typ}}$ nH	$I_R$ mA	$R_{\text{typ}}$ m $\Omega$	$V_{\text{test}}$ V DC, 2 s	Ordering code
4.7	350	300	900	750	B82720H0014A016
5.0	400	300	550	750	B82720H0014A013
10	450	200	1300	750	B82720H0014A025

**Impedance  $|Z|$  versus frequency  $f$**   
 measured with windings in parallel at 20 °C,  
 typical values



**Current derating  $I_{\text{op}}/I_R$**   
**versus ambient temperature**



## Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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